



Applications

- High Frequency Switching and Synchronous Rectification.
- DC/DC Converters.
- Power Tool Application.

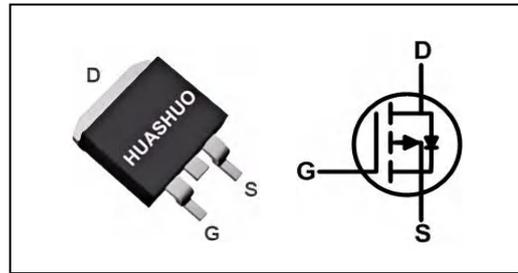
Features

- 100% EAS Guaranteed
- Green Device Available
- Fast Switching Speed
- Advanced high cell density SGT MOS Technology

Product Summary

V_{DS}	-100	V
$R_{DS(ON),typ}$	17	m Ω
I_D	-85	A

TO-263 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-85	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-50	A
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-8	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-6.3	A
I_{DM}	Pulsed Drain Current ²	-220	A
EAS	Single Pulse Avalanche Energy ³	370	mJ
I_{AS}	Avalanche Current	-90	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	205	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	0.6	$^\circ C/W$



P-Ch 100V Fast Switching MOSFETs

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-100	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-20A	---	17	20	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-2.0	-2.8	-4.0	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-80V , V _{GS} =0V , T _J =25°C	---	---	-1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
R _g	Gate Resistance	V _{DS} =-0V , V _{GS} =0V , f=1MHz	---	4.2	---	Ω
Q _g	Total Gate Charge	V _{DS} =-50V , V _{GS} =-10V , I _D =-20A	---	52	---	nC
Q _{gs}	Gate-Source Charge		---	14	---	
Q _{gd}	Gate-Drain Charge		---	13	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-50V , V _{GS} =-10V , R _G =3.3Ω, I _D =-20A	---	17	---	ns
T _r	Rise Time		---	42	---	
T _{d(off)}	Turn-Off Delay Time		---	46	---	
T _f	Fall Time		---	42	---	
C _{iss}	Input Capacitance	V _{DS} =-25V , V _{GS} =0V , f=1MHz	---	3250	---	pF
C _{oss}	Output Capacitance		---	1423	---	
C _{rss}	Reverse Transfer Capacitance		---	95	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	---	---	-85	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	I _F =-20A , di/dt=-100A/μs , T _J =25°C	---	91	---	nS
Q _{rr}	Reverse Recovery Charge		---	355	---	nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is V_{DD}=-50V, V_{GS}=-10V, L=0.1mH, I_{AS}=-90A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

P-Ch 100V Fast Switching MOSFETs

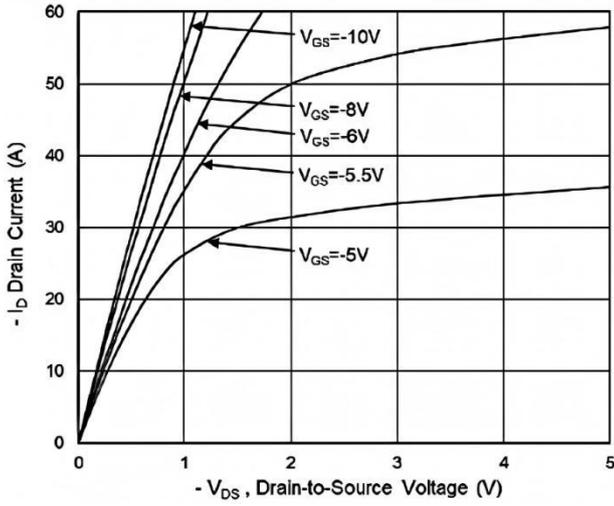


Fig.1 Typical Output Characteristics

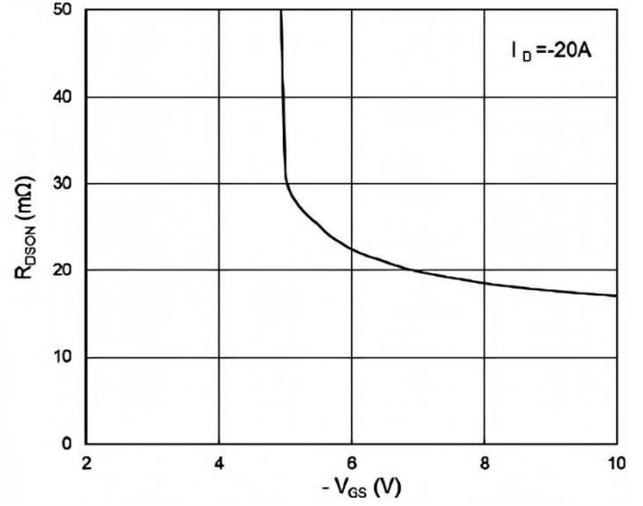


Fig.2 On-Resistance vs. G-S Voltage

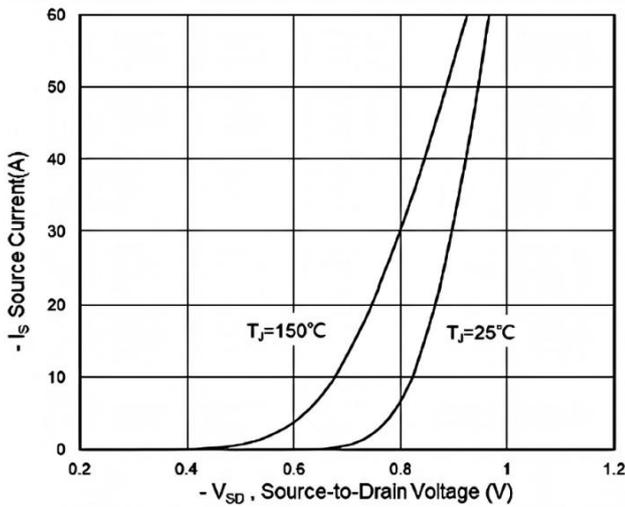


Fig.3 Typical S-D Diode Forward Voltage

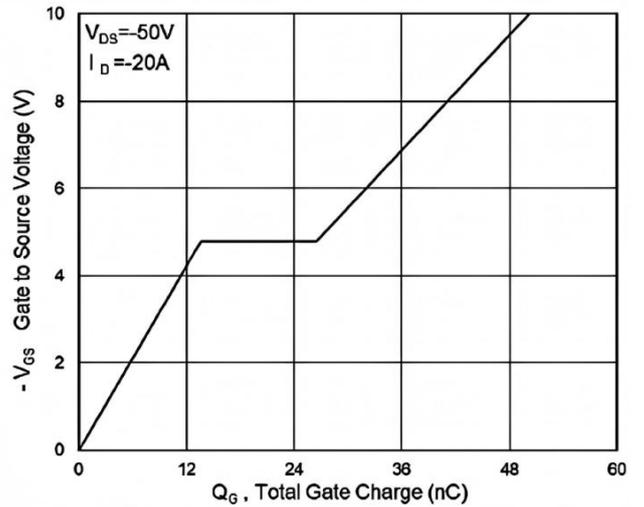


Fig.4 Gate-Charge Characteristics

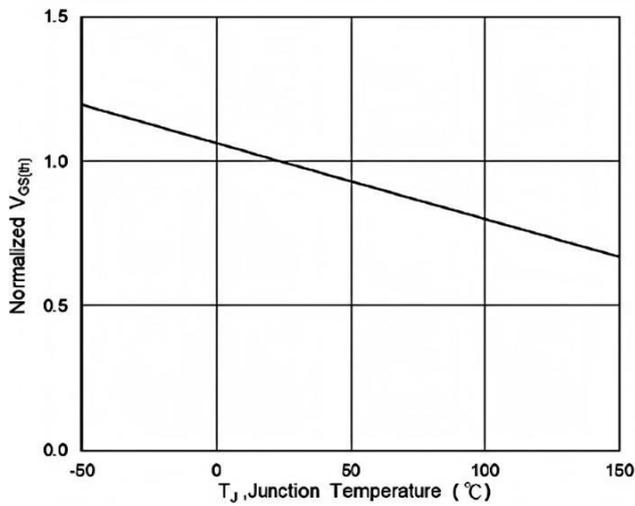


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

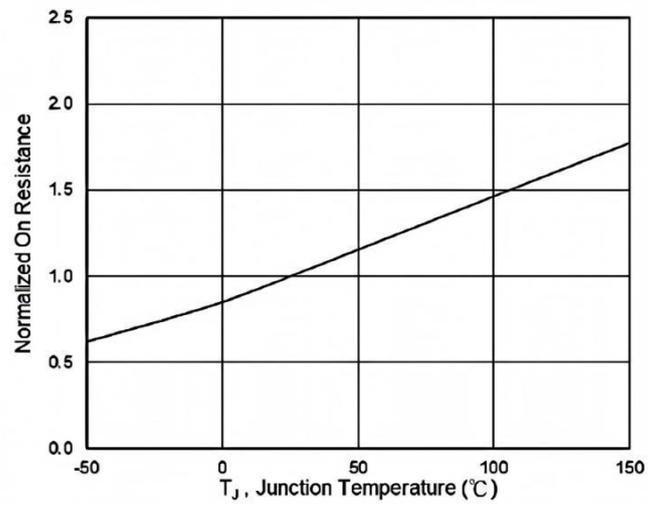


Fig.6 Normalized $R_{DS(on)}$ vs. T_J



P-Ch 100V Fast Switching MOSFETs

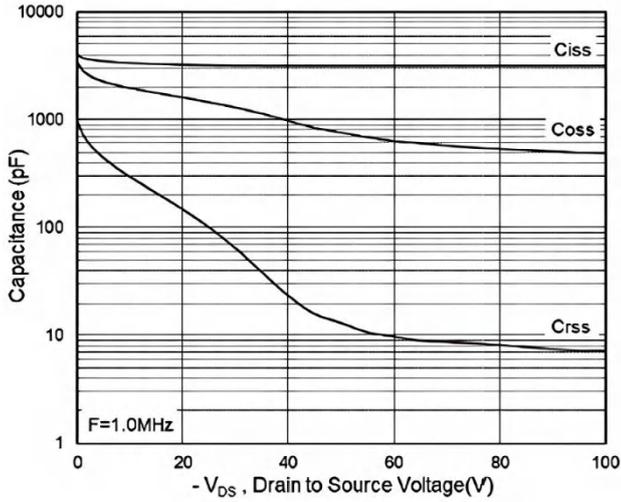


Fig.7 Capacitance

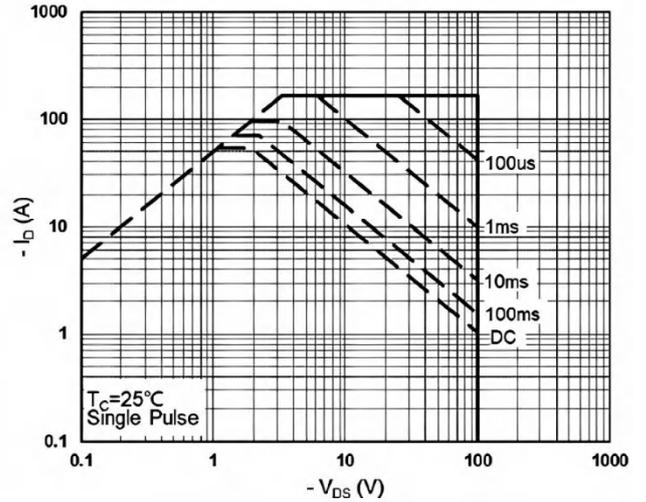


Fig.8 Safe Operating Area

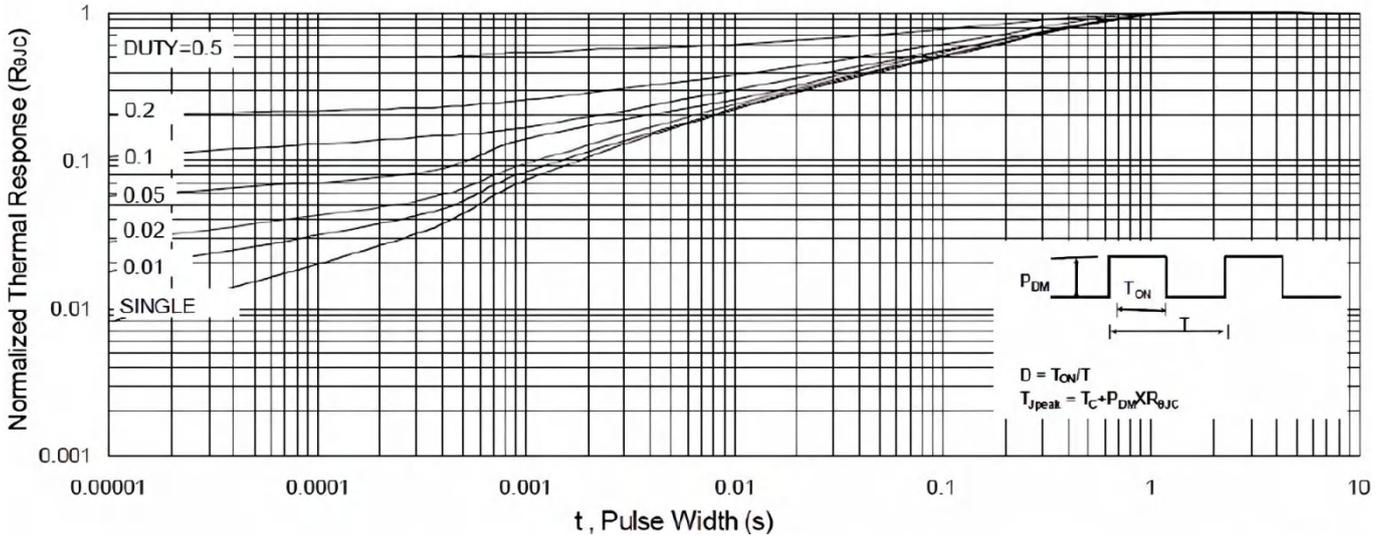


Fig.9 Normalized Maximum Transient Thermal Impedance

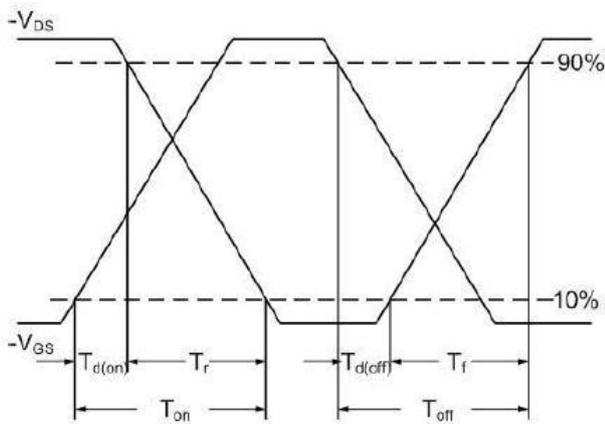


Fig.10 Switching Time Waveform

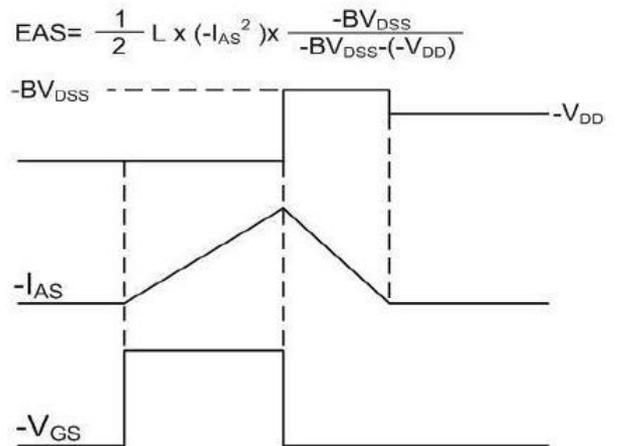


Fig.11 Unclamped Inductive Waveform



HSH0195A Marking:

